

Characterization of n-on-p devices fabricated at ITC-irst

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History

SMART collaboration

End 2003 finalized the layout

May 2004 first batch of p-on-n devices on different substrates (FZ, MCz, Cz, EPI)
Various samples sent for irradiation.

August 2004 first batch of n-on-p devices with same layout
Some samples sent for irradiation.

January 2005 irradiated samples available for test

Layout

14 + 9 + 6 Test pads including diode, MOS, gated diodes, resistor, etc.

27 MG diodes

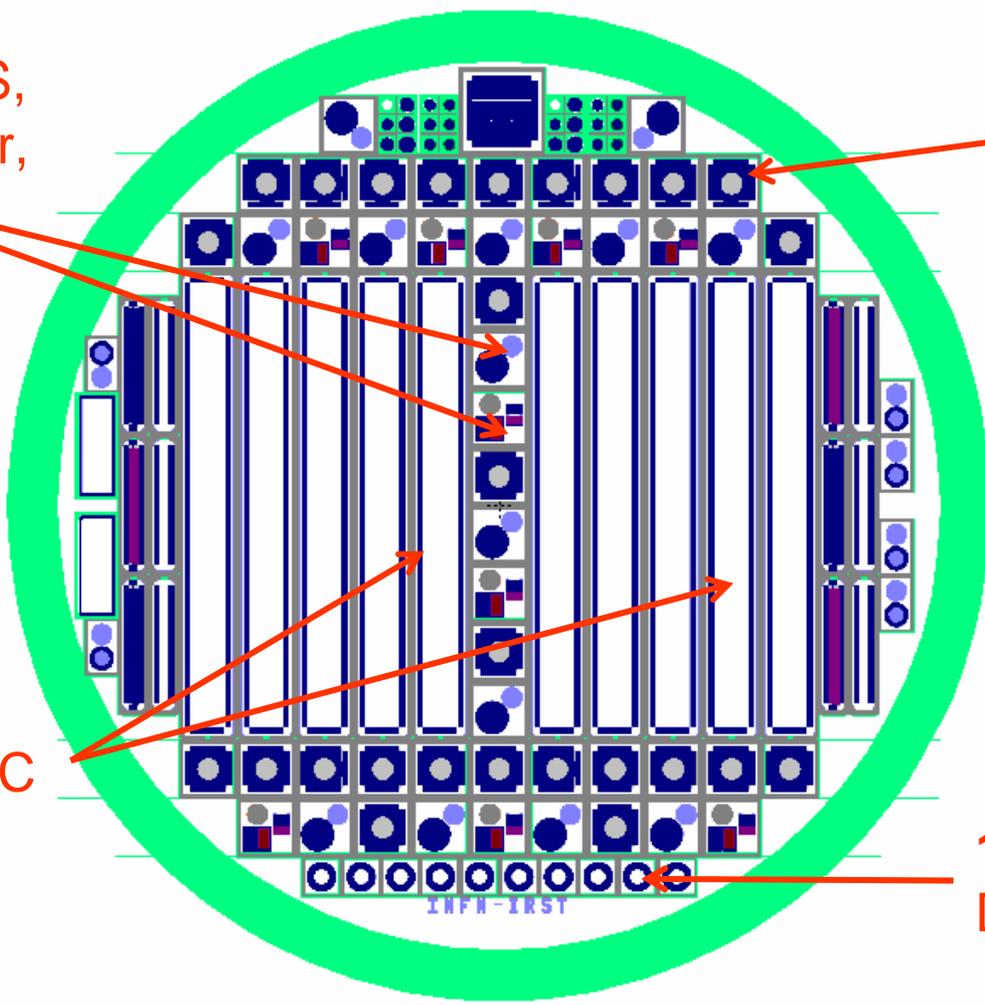
Area 13.6 mm²
die 6x6mm²

5 (pitch 50μm)
+ 5 (pitch 100μm)
Microstrip detectors AC coupled, poly-resistor biased

die 6x47mm²

10 Small MG Diodes

Area 2.3 mm²
die 4x4mm²



n-on-p batch

sub-type comments

3 FZ 525 p-spray 3E12

3 FZ 525 p-spray 5E12

3 FZ 200 p-spray 3E12

3 FZ 200 p-spray 5E12

6 MCz no OG; p-spray 3E12

5 MCz no OG; p-spray 5E12

FZ <100>
p-type
>5000Ωcm
525μm

FZ <100>
p-type
>5000Ωcm
200μm

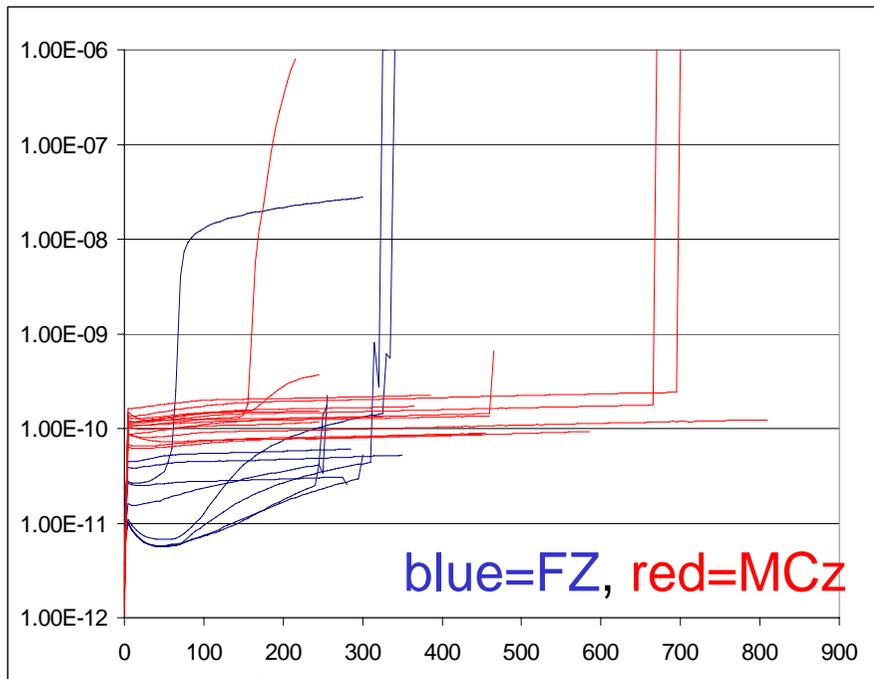
MCz <100>
p-type
>1.8kΩcm
300μm

n-on-p – IV on MG diodes (1)

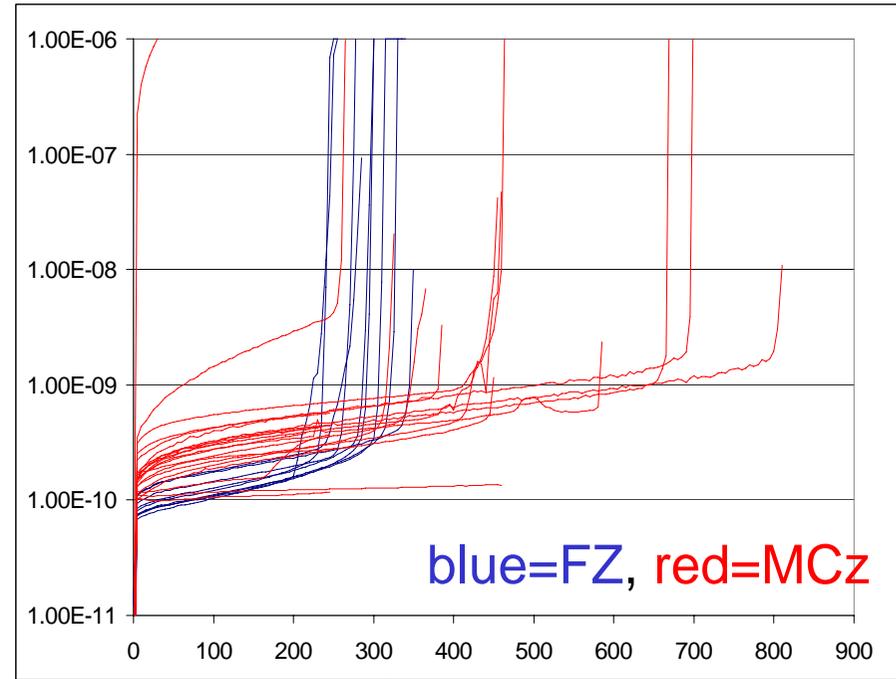
High dose p-spray

Measurements on 3 diodes per 8 wafers

Diode current (A) vs Voltage (V)



GR current (A) vs Voltage (V)



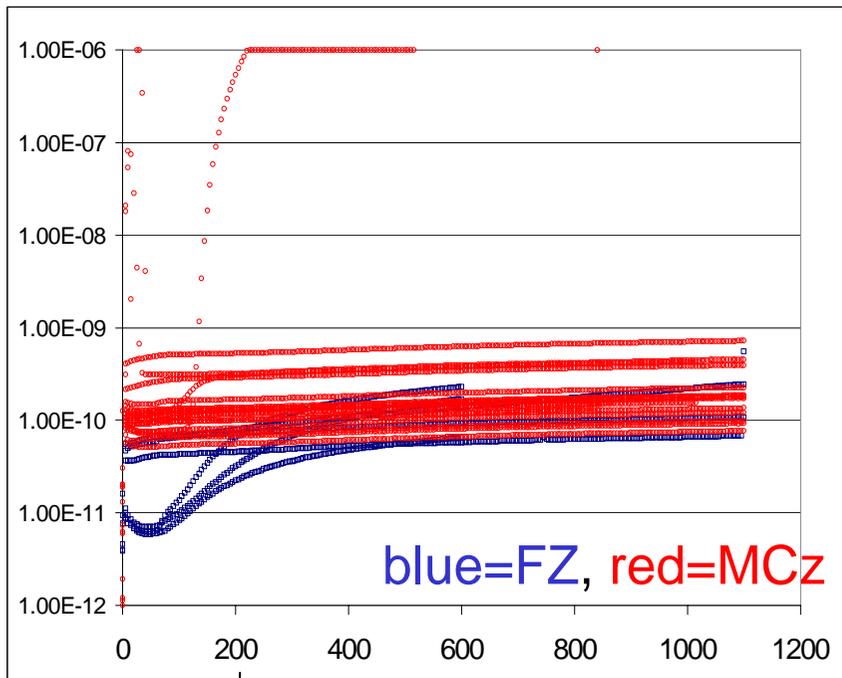
Leakage current ~ **10nA/cm²** Breakdown voltage ~ **200-300V**

n-on-p – IV on MG diodes (2)

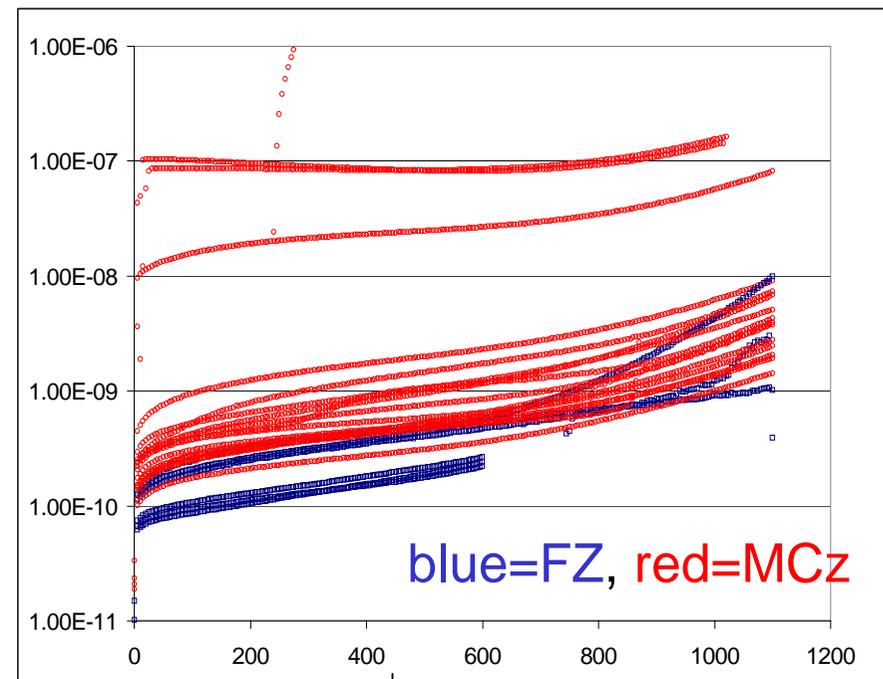
Low dose p-spray

Measurements on 3 diodes per 9 wafers

Diode current (A) vs Voltage (V)



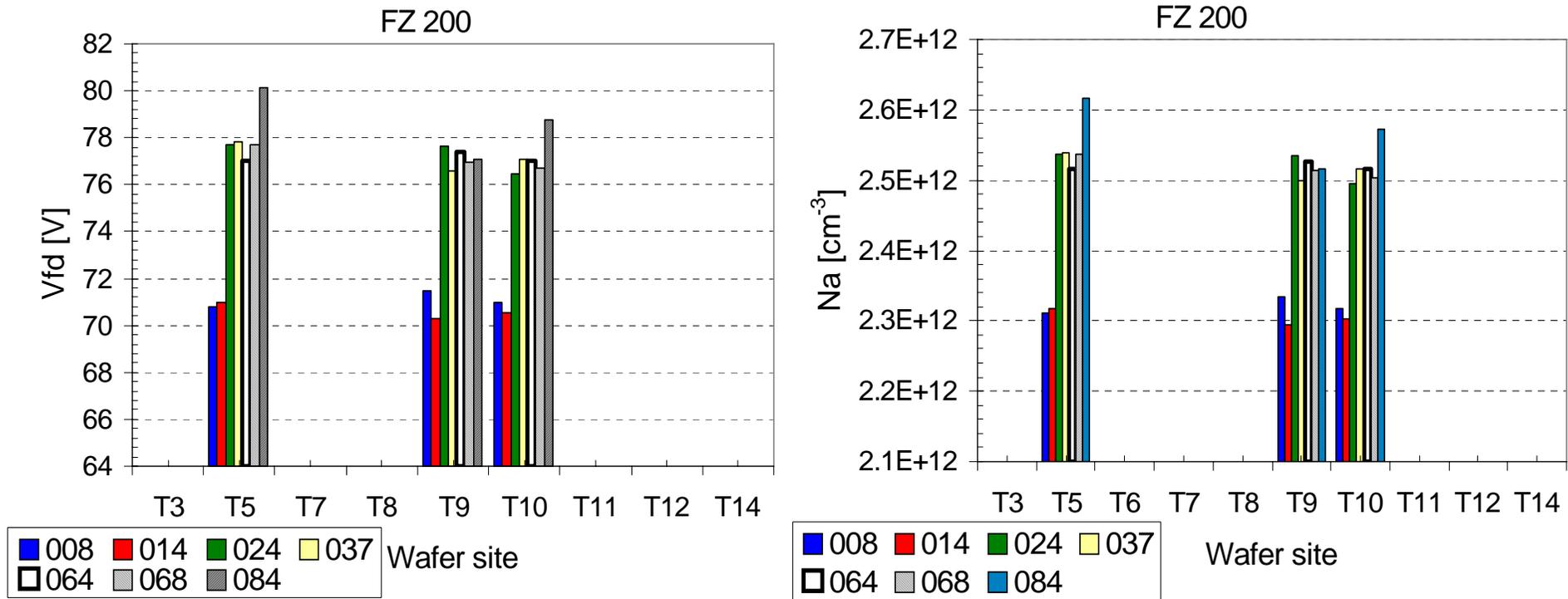
GR current (A) vs Voltage (V)



Leakage current ~ **10nA/cm²** Breakdown voltage **>1000V**

n-on-p – CV on diodes (1)

Measurements on **FZ wafers**

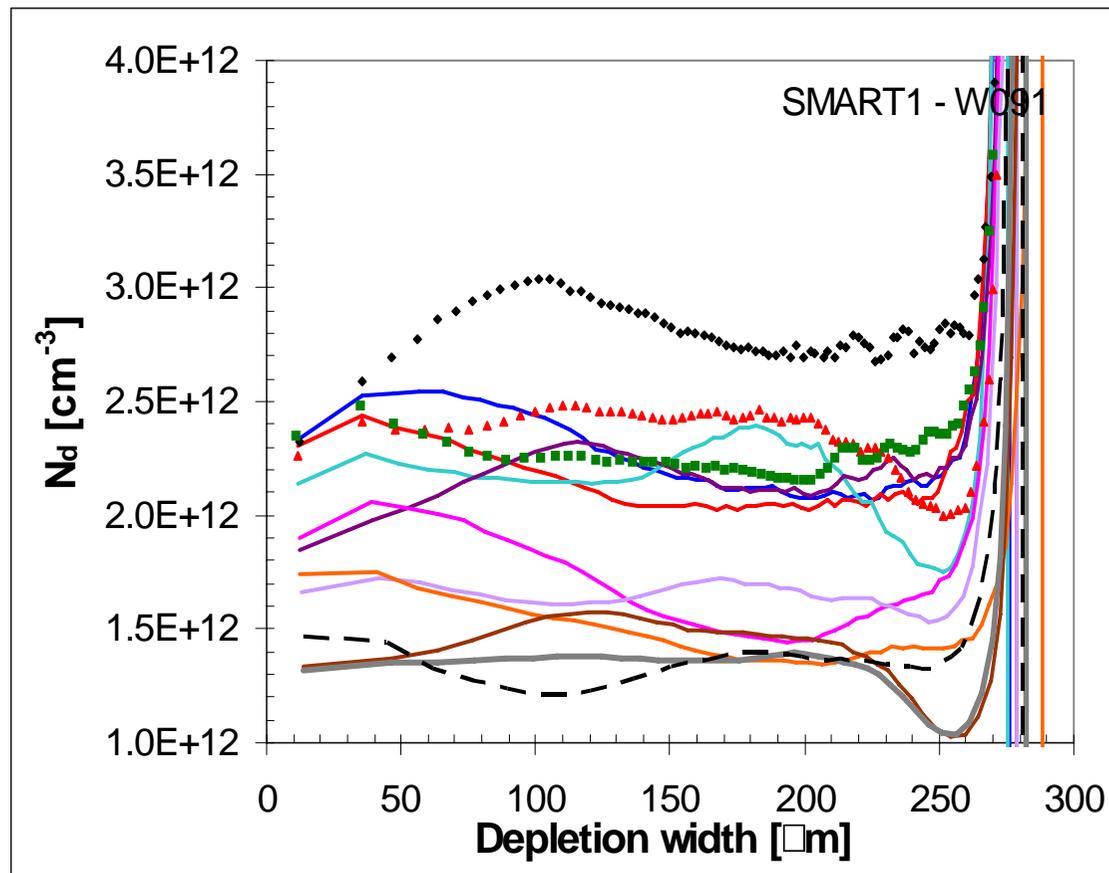


Depletion voltage very uniform at the wafer level.

n-on-p – CV on diodes (2)

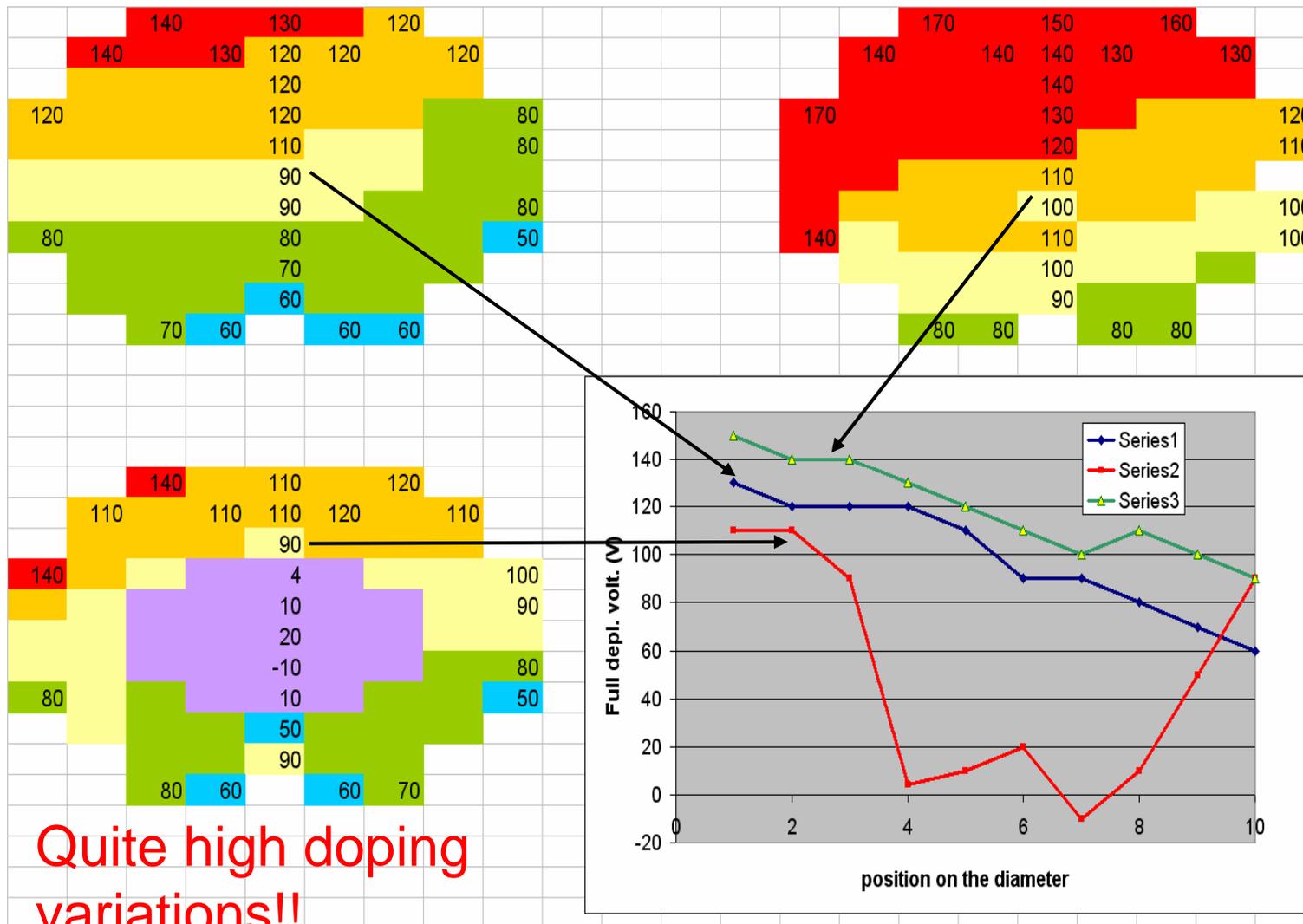
Measurements on **MCz wafers**

Example of Doping profile from CV measurement



Doping concentration lower than n-type MCz ($\sim 2 \times 10^{12}$ against 7×10^{12}) but fluctuations of the same order

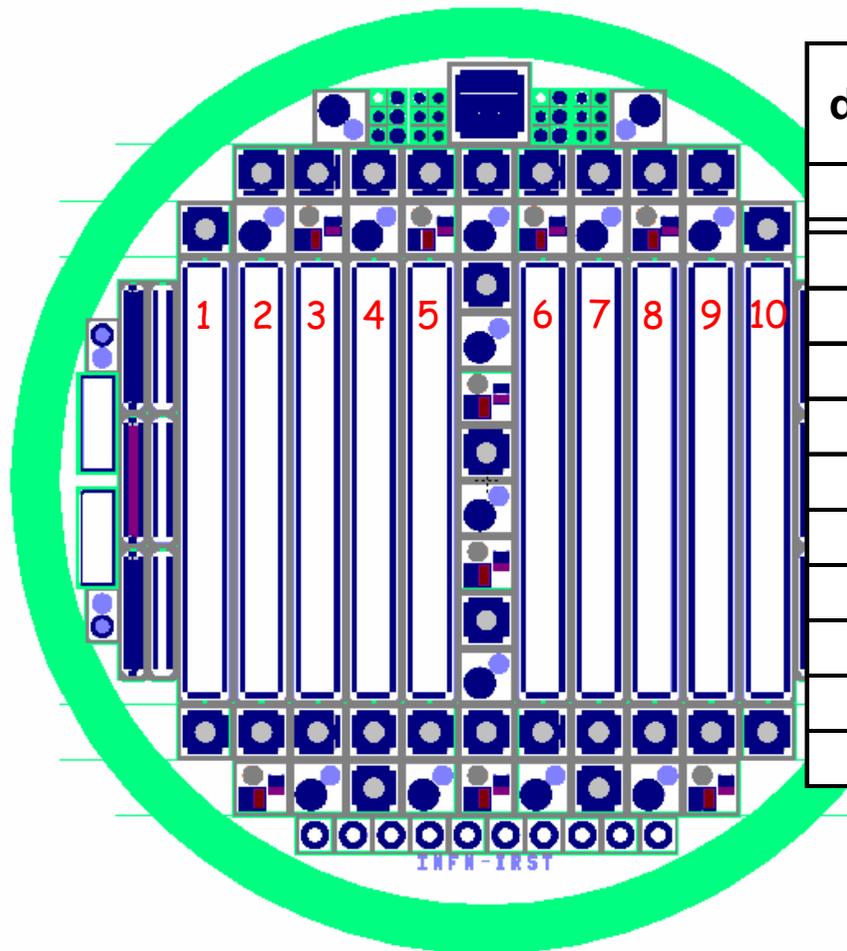
n-on-p – CV on diodes (3)



Probably due to fluctuations of the oxygen concentration.

Microstrip minisensors

- AC coupled
- poly resistor biased



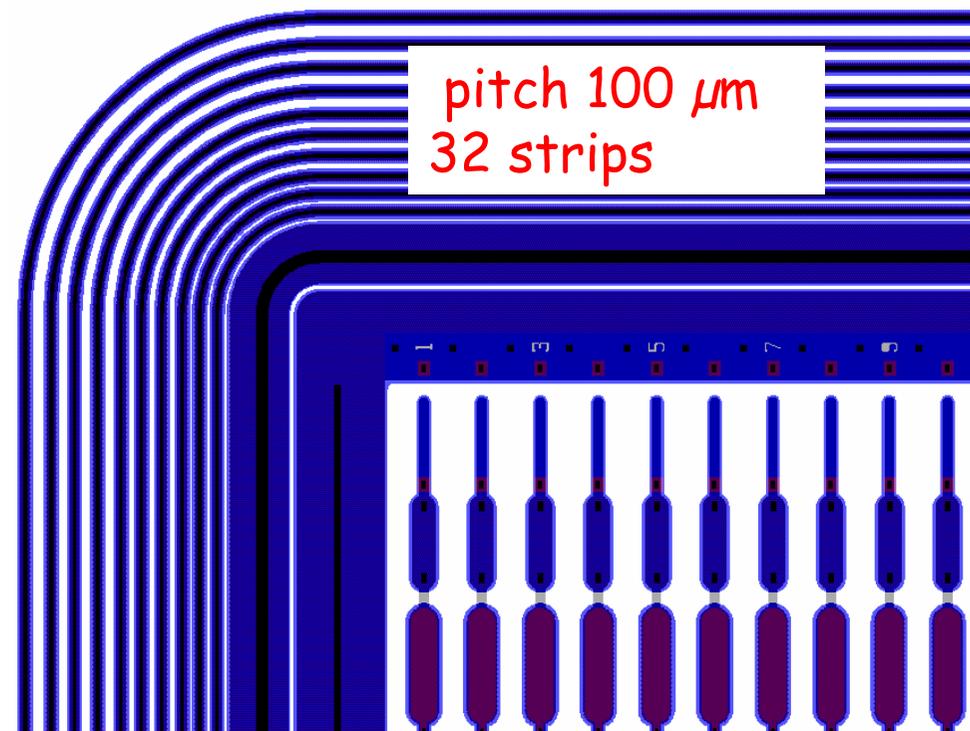
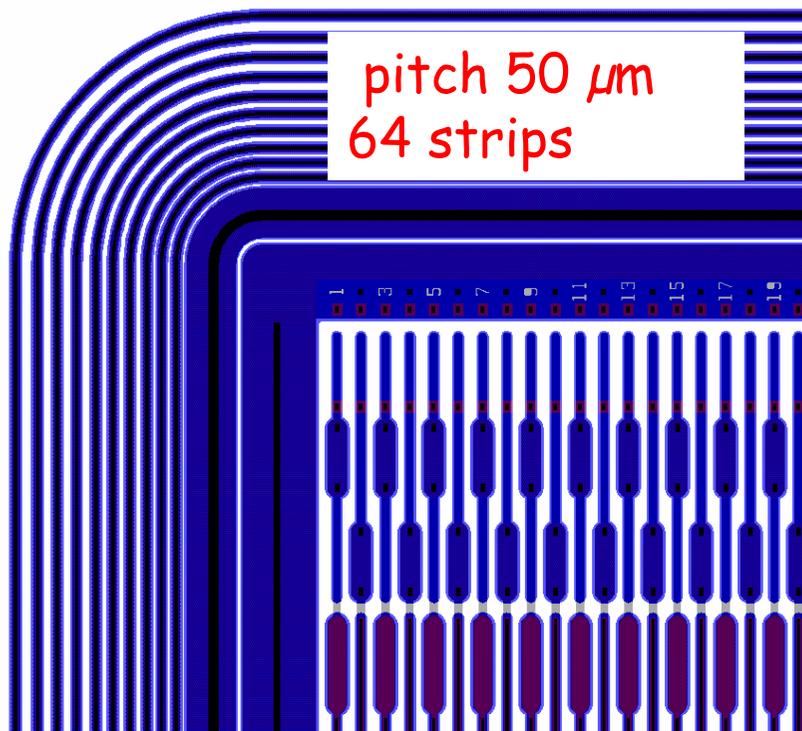
det#	pitch [um]	p ⁺ implant width [um]	polysilicon width [um]	metal width [um]
1	50	15	10	23
2	50	20	15	28
3	50	25	20	33
4	50	15	10	19
5	50	15	10	27
6	100	15	10	23
7	100	25	20	33
8	100	35	30	43
9	100	25	20	37
10	100	25	20	41

die ~6x47mm²

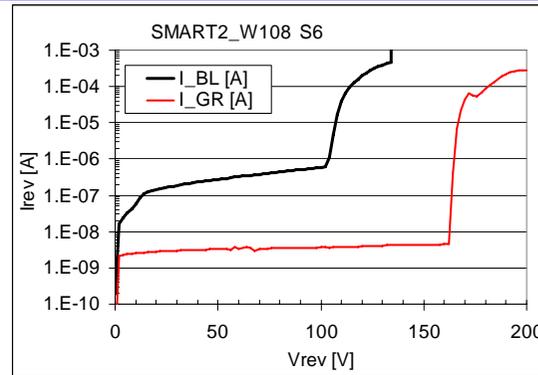
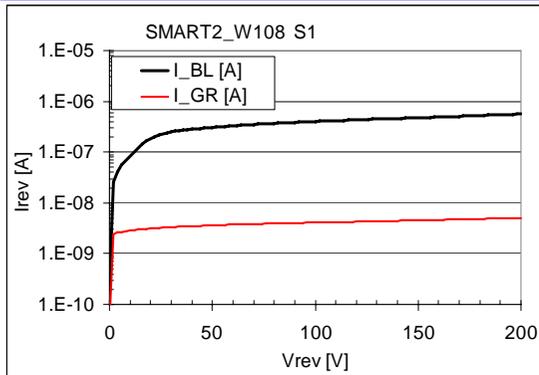
Microstrip minisensors measurements

probe-card + automatic prober

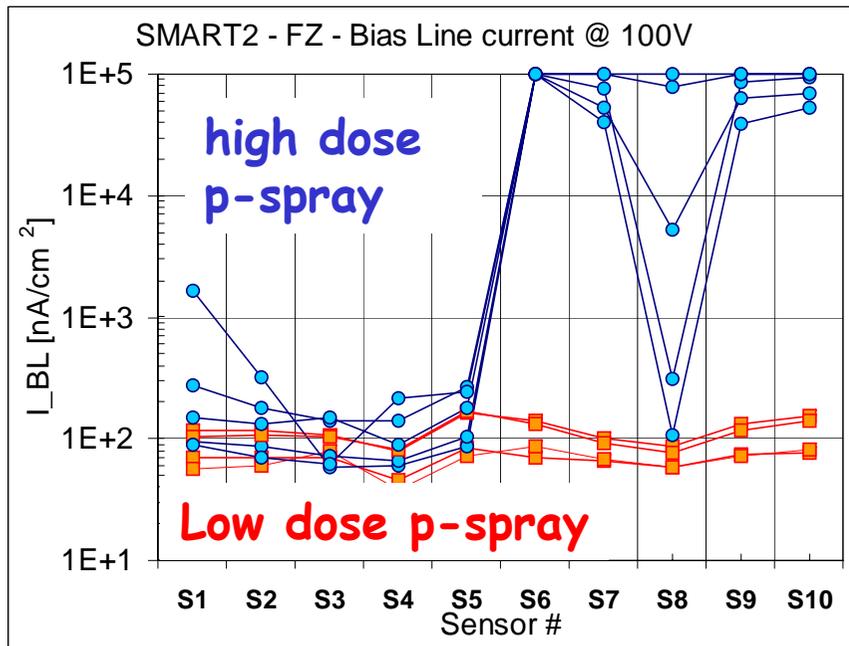
- BL&GR reverse IV
(I_{tot} , V_{rev} 0÷200 V)
- Strip current scan
(I_{strip} @ 100V V_{rev})
- Bias resistors scan
(R_{bias} @ 100V V_{rev})
- Capacitors scan
(I_{AC} @ 20V V_{cap})



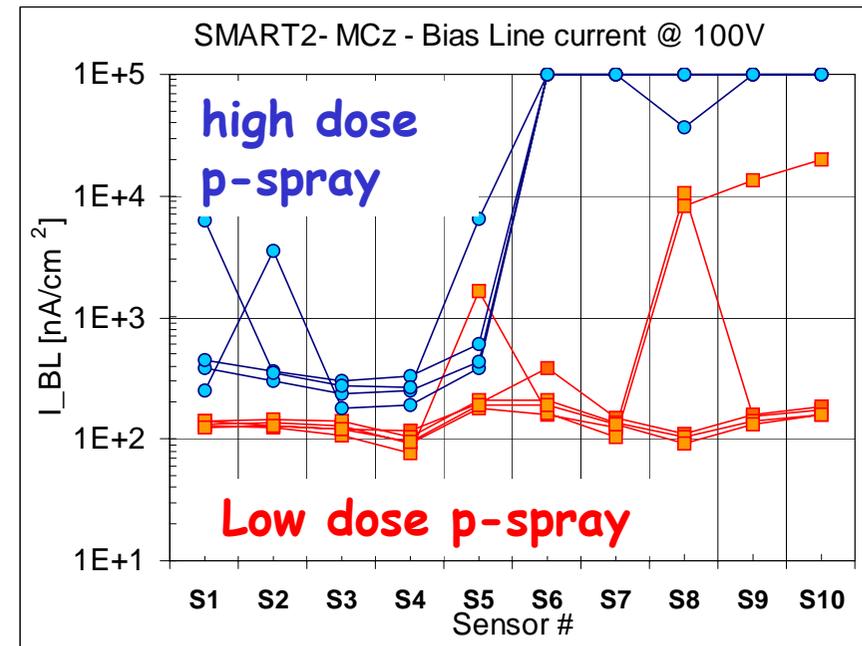
BL & GR I - V reverse currents (1)



Bias-line currents
@ 100 V



FZ wafers

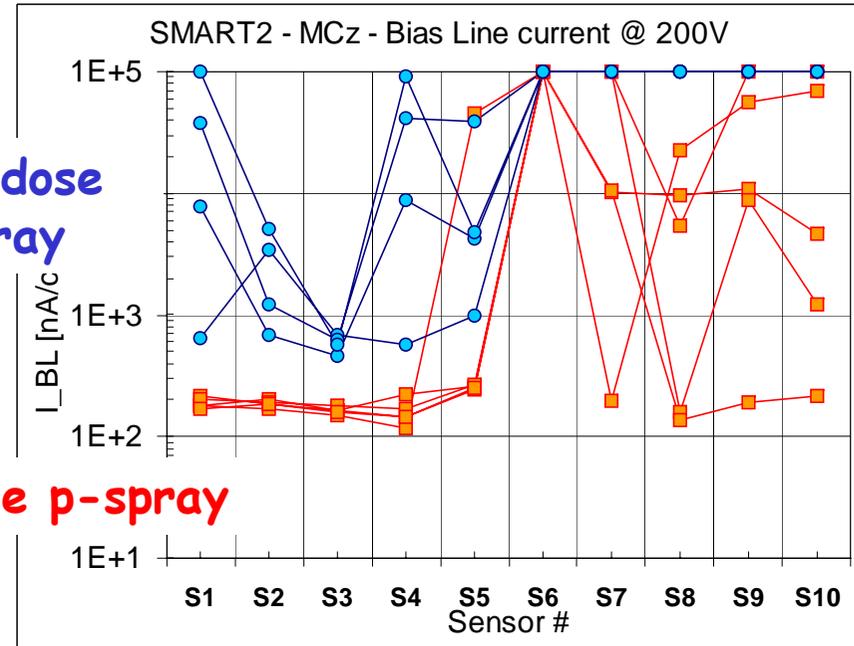
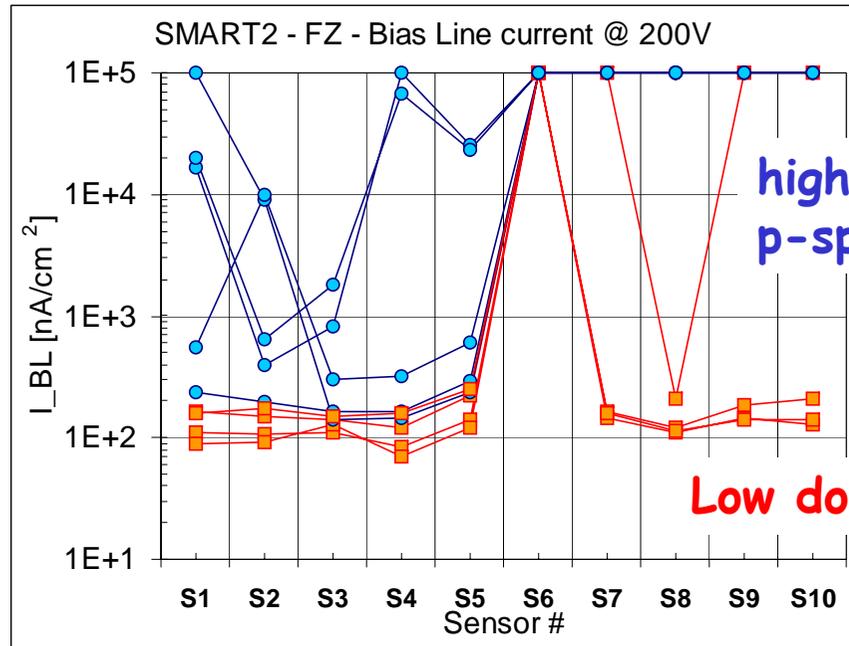


MCz wafers

BL & GR I-V reverse currents (2)

Bias-line currents @ 200 V
FZ wafers

MCz wafers

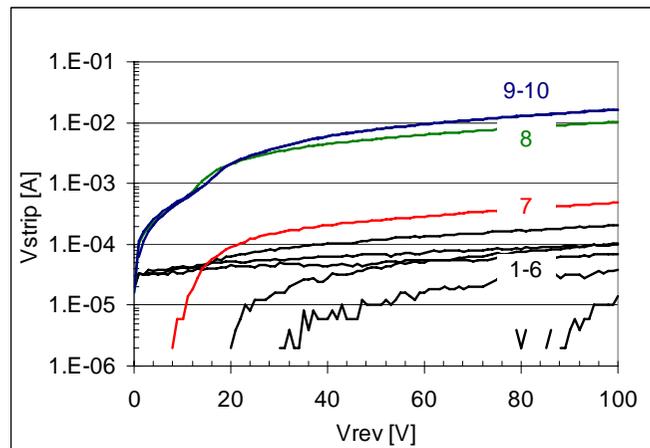
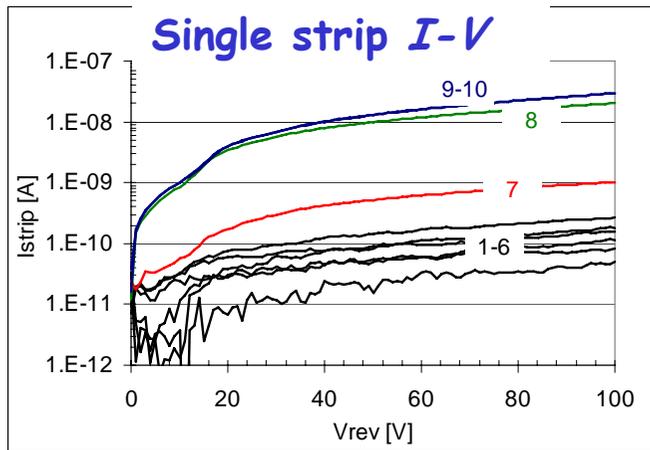


- design dependence of voltage handling capability (pitch and ...);
- low "break" voltage for high-dose p-spray;
- substrate dependence?

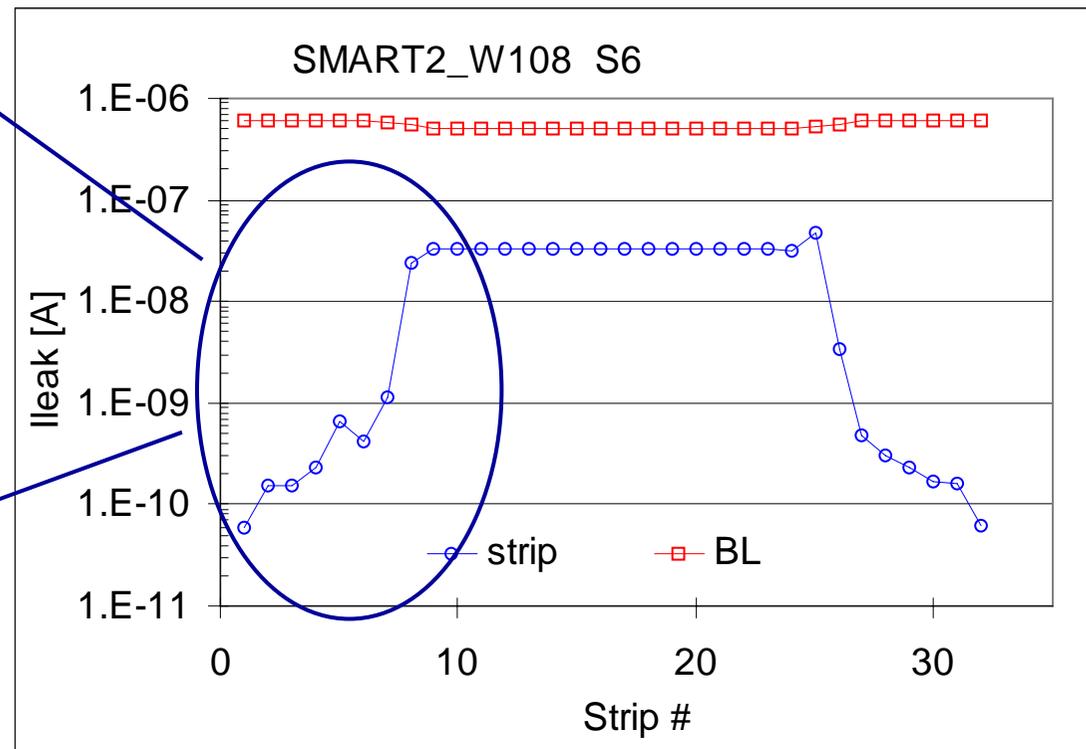
Strip current scan (100V)

Low current values on border strips

- high- and low-dose p-spray
- 50 μm and 100 μm pitch
- p and n substrates

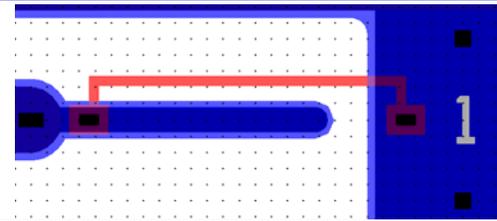
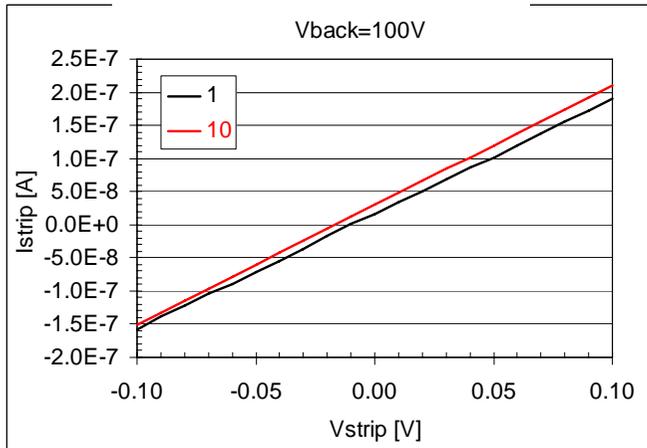


Floating strip potential



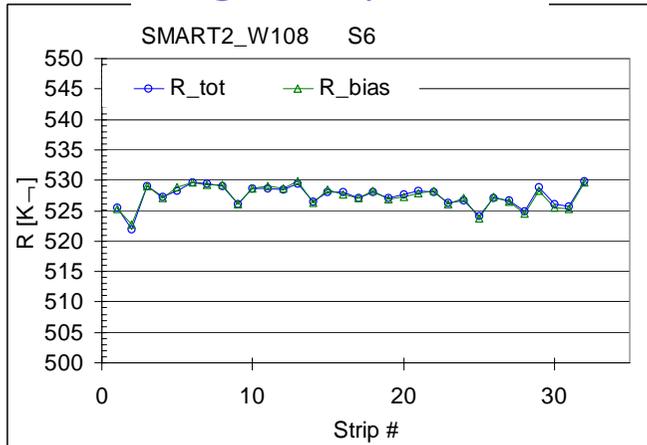
Bias resistor scan (100V)

Single strip $I-V$



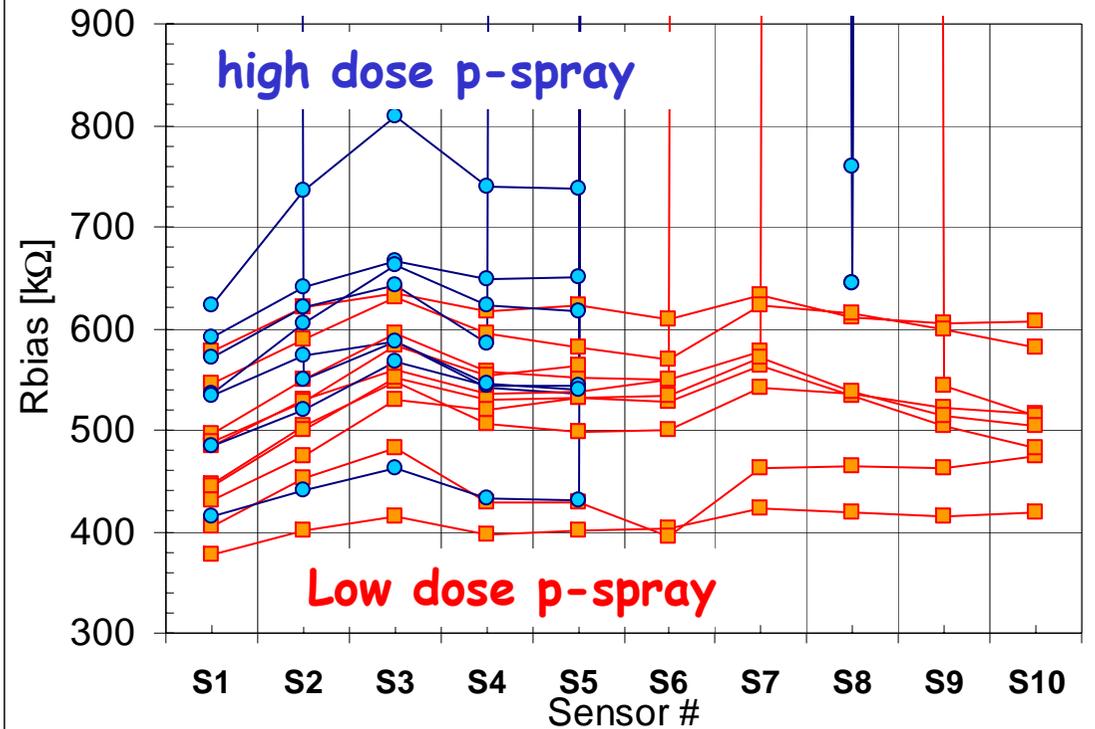
37 squares
width=6 μm

Single strip scan



Single scan uniformity: 0.2% \div 2%

SMART2 - Bias resistance mean values

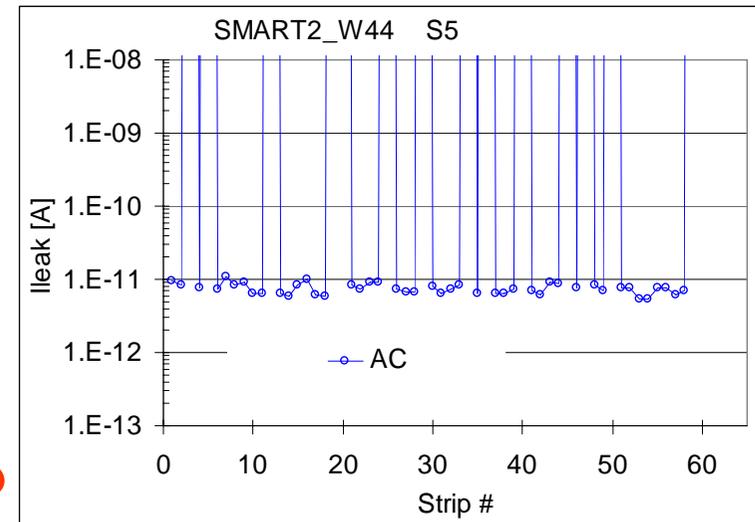
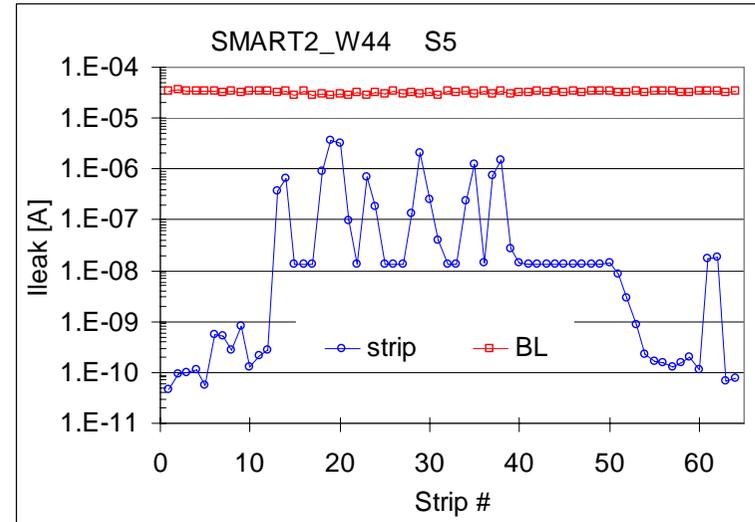


No results available for sensors with
low breakdown values

Defects

current-scan:
only few sensors

AC-scan:
~23% sensors have
broken capacitors
(mainly 50μm pitch devices)



Sub type	Split	S1	S2	S3	S4	S5	S6	S7	S8	S9	S10
FZ 525	low p-spray										
FZ 525	low p-spray										
FZ 525	low p-spray										
FZ 525	high p-spray										
FZ 525	high p-spray										
FZ 525	high p-spray										
FZ 200	low p-spray										
FZ 200	high p-spray										
FZ 200	high p-spray										
MCz	low p-spray										
MCz	low p-spray										
MCz	low p-spray										
MCz	low p-spray										
MCz	low p-spray										
MCz	high p-spray										
MCz	high p-spray										
MCz	high p-spray										
MCz	high p-spray										

← batch or sub problem?

No AC-defects are present for p-on-n devices

Conclusion

Problems on n-on-p production:

- non-uniformity of the depletion voltage (MCz subs)
- design/p-spray-dose interaction (\rightarrow p-stop...?)

To be verified:

- effectiveness of actual p-spray

Samples available for the collaboration.